



Technical drawing of a cross-section of a multi-layer printed circuit board (PCB) showing internal layers and prepreg. The drawing includes dimensions for layer thicknesses and overall board thickness. Key features include a central prepreg layer (半田付け部) and contact areas (コンタクト部). Dimensions are given in millimeters with tolerances.

Dimensions (mm):

- Top prepreg layer: $3.5^{+0.5}$
- Core layer: 7.4
- Bottom prepreg layer: $5.8^{+0.3}$
- Overall thickness: 2.54
- Prepreg layer thickness: 2.83
- Contact area thickness: 1.88

Labels:

- 半田付け部 (Prepreg layer)
- コンタクト部 (Contact area)

Material specifications (mm):

0.7 Y	0.6 W
0.6 Z	0.8 X

注記

1. 材料 ウエハー : ガラス繊維 15% 入り PBTP (UL94V-0), 黒色
 ピン : 黄銅, サイズ ρ0.635
2. 嵌合相手 : 5320 シリーズ
3. 使用符号の説明 5332 - N *

○説明 5332 - N
 ベースナンバー _____
 極数 _____
 ピンのメッキコード _____

	コード:*	△マークの色	コンタクト部	半田付け部	下地メッキ
	GS3	青	金 0.25μm MIN.	半田 3μm MIN.	ニッケル 1μm MIN.
LEAD-FREE	GS17F	黄	金 0.1μm MIN.	錫 1μm MIN.	
LEAD-FREE	GS37F	青	金 0.25μm MIN.		
LEAD-FREE	T2	黒	錫 1μm MIN.		ニッケル 0.5μm MIN.

60	73.66	81.26	83.16	63.50
50	60.96	68.56	70.46	50.80
40	48.26	55.86	57.76	38.10
34	40.64	48.24	50.14	30.48
30	35.56	43.16	45.06	25.40
26	30.48	38.08	39.98	—H—
20	22.86	30.46	32.36	—H—
16	17.78	25.38	27.28	—H—
14	15.24	22.84	24.74	—H—
10	10.16	17.76	19.66	—H—
極数	A 寸法	B 寸法	C 寸法	D 寸法

REVISED EC NO: J2012-0302 DRWN:HTONEGAWA CHKD:INI TSU APPR:MYAGI	2011/08/31 2011/08/31 2011/09/07	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
			10 UNDER ± 0.2	H.HIRAMOTO 1990/06/19	TITLE QIK FLECS WAFER ASSY ST JAPANESE ONLY				
			10 OVER 30 UNDER ± 0.25	CHECKED BY DATE M.SASAO					
			30 OVER ± 0.3	APPROVED BY DATE H.IKESUGI	 MOLEX INCORPORATED				
			ANGULAR ±3 °	MATERIAL NO.					DOCUMENT NO.
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 2 OF 2		SD-5332-001		1 OF 2
K		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

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Rev. D 2004/04/02

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DRWN:HTONEGAWA 2011/08/31
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DESCRIPTION
REV

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER ± 0.2

10 OVER 30 UNDER ± 0.25

30 OVER ± 0.3

ANGULAR ± 3 °

DRAFT WHERE APPLICABLE
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DIMENSION STYLE
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DRAWN BY DATE
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SCALE
2:1

DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

TITLE
QIK FLECS WAFER ASSY ST.
JAPANESE ONLY

molex MOLEX INCORPORATED

DOCUMENT NO.
SD-5332-001

SHEET NO.
2 OF 2

39-53-6266	5332-26GS37F	39-28-5261	5332-26T2	26
↗	↗	↓ -5201	-20T2	20
↗	↗	39-28-5141	5332-14T2	14
EDP NO.	ENG. NO.	EDP NO.	ENG. NO.	極 数
5332-NGS37F	-LEAD FREE-	5332-NT2	-LEAD FREE-	
39-53-6344	5332-34GS17F	↗		34
↓ -6264	↓ -26GS17F	39-26-7267	5332-26GS3	26
-6204	-20GS17F	↗	↗	20
↓ -6144	↓ -14GS17F	↗	↗	14
39-53-6104	5332-10GS17F	↗	↗	10
EDP NO.	ENG. NO.	EDP NO.	ENG. NO.	極 数
5332-NGS17F	-LEAD FREE-	5332-NGS3		

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Rev. D 2004/04/02

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